12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20150302001
SPIL Taiwan Ball Placement Flux
Change Notification / Sample Request

Dear Customer:

TI has decided to cancel this PCN. The devices included in PCN#20150302001 were not impacted by the solder flux change. The devices have always, from initial release date, been supplied with the solder flux WF6317 – Therefore there is no change planned. Please disregard PCN # 2010302001. We apoligize for any confusion.

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

PCN# 20150302001
Attachment: 1

Products Affected:

According to our records, there are the affected device(s) that you have purchased within the past twenty-four (24) months. Technical details of this Product Change follow on the next page(s).

PCN Number:	20150302001	**PCN Date:**	05/06/2015
Title:	DPP260x Solder Ball Flux Change		
Customer Contact:	dlp_pcn_team@ti.com	**Dept:**	DLP® CQE
Proposed 1st Ship Date:	7/15/2015	**Estimated Sample Availability:**	4/1/2015

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Material
☒	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

PCN Details

Description of Change:

TI has decided to cancel this PCN. The flux is not changing and has been WF6317 since initial production.

DPP260x solder ball flux is changing.
SPIL Taiwan is changing flux type from FW6400 to WF6317.

Reason for Change:

1) Improve overall manufacturability
2) Better inventory management, as WF6317 is now SPILs standard.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None.

Changes to product identification resulting from this PCN:

None.

Product Affected:

Device	Part Number
DPP2601	2510464-0001
DPP2601	2510464-0001R
DLPC2607	2510465-0001
DLPC2607	2510465-0001R
DLPC300ZVB	DLPC300ZVB

Qualification Data

This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification: ☐ **Plan** ☒ **Test Results**

Test Criteria:

- Ball Surface – for discoloration (not allowed).
- Flux Residue – (not allowed).
- Ball Shear Test
- Ball Pull Test

Monitor Plan:

5 Lots Tested		
Item	Sample Size	Criteria
Missing ball	100%/ lot	>99.5%
Big ball	100%/ lot	>99.5%
Ball bridge	100%/ lot	>99.5%
Flux residue	100%/ lot	Not allow
Ball pull/ ball shear	8 ball/ pcs/ 3pcs/ lot	> SPEC criteria

Qualification Testing Results:

- A total of 9,984 parts were tested.
- All results passed.
- No Flux residue observed through SEM,

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
DLP PCN Team	dlp_pcn_team@ti.com
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com